

EIGHT OUTPUT DIFFERENTIAL BUFFER FOR PCIE GEN1 AND GEN2

ICS9DB803D

General Description

The ICS9DB803D is compatible with the Intel DB800v2 Differential Buffer Specification. This buffer provides 8 PCI-Express Gen2 clocks. The ICS9DB803D is driven by a differential output pair from a CK410B+, CK505 or CK509B main clock generator.

Recommended Application

DB800v2 compatible part with PCle Gen1 and Gen2 Support

Output Features

- 8 0.7V current-mode differential output pairs
- Supports zero delay buffer mode and fanout mode
- · Bandwidth programming available
- 50-100 MHz operation in PLL mode
- 50-400 MHz operation in Bypass mode

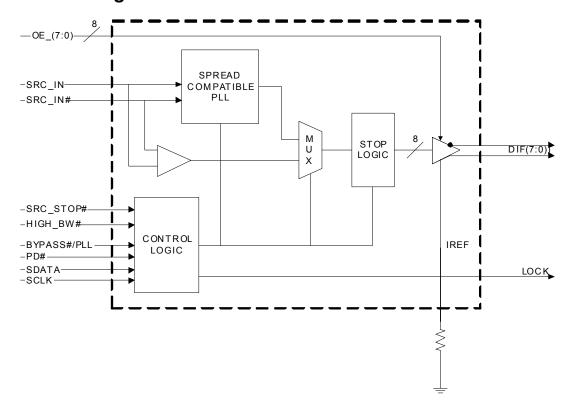
Features/Benefits

- Spread spectrum modulation tolerant, 0 to -0.5% down spread and +/- 0.25% center spread
- Supports undriven differential outputs in PD# and SRC_STOP# modes for power management

Key Specifications

- Outputs cycle-cycle jitter < 50ps
- Output to Output skew <50ps
- Phase jitter: PCIe Gen1 < 86ps peak to peak
- Phase jitter: PCle Gen2 < 3.0/3.1ps rms

Functional Block Diagram



Note: Polarities shown are for OE_INV=0.

Pin Configuration

SRC_DIV# 1	CS9DB803 (Same as ICS9DB108)	48 VDDA 47 GNDA 46 IREF 45 LOCK 44 OE_7 43 OE_4 42 DIF_7 41 DIF_7# 40 OE_INV 39 VDD 38 DIF_6 37 DIF_6# 36 OE_6 35 OE_5 34 DIF_5 33 DIF_5# 32 GND 31 VDD 30 DIF_4 29 DIF_4# 28 HIGH_BW# 27 DIF_STOP#	SRC_DIV# VDDR GND SRC_IN# OE0# OE3# DIF_0# GND VDD DIF_1# OE1# OE2# DIF_2# GND VDD DIF_2# GND VDD DIF_3# BYPASS#/PLL	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21	(Same as ICS3DB801) (28 44 43 40 40 40 40 40 40 40 40 40 40 40 40 40	VDDA GNDA IREF LOCK OE7# OE4# DIF_7 DIF_7# OE_INV VDD DIF_6 DIF_6# OE5# DIF_5 DIF_5# GND VDD DIF_4 DIF_4 DIF_4# HIGH_BW; DIF_STOP
DIF_3# 2	21	28 HIGH_BW#	DIF_3#	21	28	HIGH_BW#
BYPASS#/PLL 2 SCLK 2 SDATA 2	23	27 DIF_STOP# 26 PD# 25 GND	BYPASS#/PLL SCLK SDATA	23	26	DIF_STOP PD GND
OE_INV = 0			•	OE_IN		ı

Power Groups

Pin N	Number	Description		
VDD	GND	Description		
2	3	SRC_IN/SRC_IN#		
6,11,19,	10,18, 25,32	DIF(7:0)		
31,39	10, 10, 23,32	DII (7.0)		
N/A	47	IREF		
48	47	Analog VDD & GND for PLL core		

Polarity Inversion Pin List Table

Dina	OE	_INV
Pins	0	1
6	OE_0	OE_0#
7	OE_3	OE_3#
14	OE_1	OE_1#
15	OE_2	OE_2#
26	PD#	PD
27	DIF_STOP#	DIF_STOP
35	OE_5	OE_5#
36	OE_6	OE_6#
43	OE_4	OE_4#
44	OE_7	OE_7#

Pin Descriptions for OE_INV=0

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
1	SRC_DIV#	IN	Active low Input for determining SRC output frequency SRC or SRC/2. 0 = SRC/2, 1= SRC
2	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
3	GND	PWR	Ground pin.
4	SRC_IN	IN	0.7 V Differential SRC TRUE input
5	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
6	OE_0	IN	Active high input for enabling output 0. 0 =disable outputs, 1= enable outputs
7	OE_3	IN	Active high input for enabling output 3. 0 =disable outputs, 1= enable outputs
8	DIF_0	OUT	0.7V differential true clock output
9	DIF_0#	OUT	0.7V differential Complementary clock output
10	GND	PWR	Ground pin.
11	VDD	PWR	Power supply, nominal 3.3V
12	DIF_1	OUT	0.7V differential true clock output
13	DIF_1#	OUT	0.7V differential Complementary clock output
14	OE_1	IN	Active high input for enabling output 1. 0 =disable outputs, 1= enable outputs
15	OE_2	IN	Active high input for enabling output 2. 0 =disable outputs, 1= enable outputs
16	DIF_2	OUT	0.7V differential true clock output
17	DIF_2#	OUT	0.7V differential Complementary clock output
18	GND	PWR	Ground pin.
19	VDD	PWR	Power supply, nominal 3.3V
20	DIF_3	OUT	0.7V differential true clock output
21	DIF_3#	OUT	0.7V differential Complementary clock output
22	BYPASS#/PLL	IN	Input to select Bypass(fan-out) or PLL (ZDB) mode 0 = Bypass mode, 1= PLL mode
23	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
24	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.

Pin Descriptions for OE_INV=0 (cont.)

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
25	GND	PWR	Ground pin.
			Asynchronous active low input pin used to power down the
26	PD#	IN	device. The internal clocks are disabled and the VCO and
			the crystal osc. (if any) are stopped.
27	DIF_STOP#	IN	Active low input to stop differential output clocks.
28	HIGH_BW#	PWR	3.3V input for selecting PLL Band Width 0 = High, 1= Low
29	DIF_4#	OUT	0.7V differential Complementary clock output
30	DIF_4	OUT	0.7V differential true clock output
			1
31	VDD	PWR	Power supply, nominal 3.3V
32	GND	PWR	Ground pin.
33	DIF_5#	OUT	0.7V differential Complementary clock output
34	DIF_5	OUT	0.7V differential true clock output
35	OE_5	IN	Active high input for enabling output 5.
			0 =disable outputs, 1= enable outputs
36	OE_6	IN	Active high input for enabling output 6.
07	DIE 0"	OUT	0 =disable outputs, 1= enable outputs
37	DIF_6#	OUT	0.7V differential Complementary clock output
38	DIF_6	OUT	0.7V differential true clock output
39	VDD	PWR	Power supply, nominal 3.3V
40	OE_INV	IN	This latched input selects the polarity of the OE pins.
			0 = OE pins active high, 1 = OE pins active low (OE#)
41	DIF_7#	OUT	0.7V differential Complementary clock output
42	DIF_7	OUT	0.7V differential true clock output
43	OE_4	IN	Active high input for enabling output 4.
			0 =disable outputs, 1= enable outputs Active high input for enabling output 7.
44	OE_7	IN	0 =disable outputs, 1= enable outputs
45	LOCK	OUT	3.3V output indicating PLL Lock Status. This pin goes high
45	LOOK	001	when lock is achieved.
			This pin establishes the reference for the differential current-
, .			mode output pairs. It requires a fixed precision resistor to
46	IREF	IN	ground. 475ohm is the standard value for 100ohm
			differential impedance. Other impedances require different
			values. See data sheet.
47	GNDA	PWR	Ground pin for the PLL core.
48	VDDA	PWR	3.3V power for the PLL core.

ICS9DB803D

Pin Descriptions for OE_INV=1

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
1	SRC_DIV#	IN	Active low Input for determining SRC output frequency SRC or SRC/2. 0 = SRC/2, 1= SRC
2	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
3	GND	PWR	Ground pin.
4	SRC_IN	IN	0.7 V Differential SRC TRUE input
5	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
6	OE0#	IN	Active low input for enabling DIF pair 0. 1 =disable outputs, 0 = enable outputs
7	OE3#	IN	Active low input for enabling DIF pair 3. 1 =disable outputs, 0 = enable outputs
8	DIF_0	OUT	0.7V differential true clock output
9	DIF_0#	OUT	0.7V differential Complementary clock output
10	GND	PWR	Ground pin.
11	VDD	PWR	Power supply, nominal 3.3V
12	DIF_1	OUT	0.7V differential true clock output
13	DIF_1#	OUT	0.7V differential Complementary clock output
14	OE1#	IN	Active low input for enabling DIF pair 1. 1 =disable outputs, 0 = enable outputs
15	OE2#	IN	Active low input for enabling DIF pair 2. 1 =disable outputs, 0 = enable outputs
16	DIF_2	OUT	0.7V differential true clock output
17	DIF_2#	OUT	0.7V differential Complementary clock output
18	GND	PWR	Ground pin.
19	VDD	PWR	Power supply, nominal 3.3V
20	DIF_3	OUT	0.7V differential true clock output
21	DIF_3#	OUT	0.7V differential Complementary clock output
22	BYPASS#/PLL	IN	Input to select Bypass(fan-out) or PLL (ZDB) mode 0 = Bypass mode, 1= PLL mode
23	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
24	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.

5

Pin Descriptions for OE_INV=1 (cont.)

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
25	GND	PWR	Ground pin.
			Asynchronous active high input pin used to power down the device.
26 PD		IN	The internal clocks are disabled and the VCO is stopped.
27	DIF_STOP	IN	Active High input to stop differential output clocks.
21	DIF_STOF	IIN	3.3V input for selecting PLL Band Width
28	HIGH_BW#	PWR	0 = High, 1= Low
29	DIF_4#	OUT	0.7V differential Complementary clock output
30	DIF_4	OUT	0.7V differential true clock output
31	VDD	PWR	Power supply, nominal 3.3V
32	GND	PWR	Ground pin.
33	DIF_5#	OUT	0.7V differential Complementary clock output
34	DIF_5	OUT	0.7V differential true clock output
		18.1	Active low input for enabling DIF pair 5.
35	OE5#	IN	1 =disable outputs, 0 = enable outputs
26	056#	INI	Active low input for enabling DIF pair 6.
36	OE6#	IN	1 =disable outputs, 0 = enable outputs
37	DIF_6#	OUT	0.7V differential Complementary clock output
38	DIF_6	OUT	0.7V differential true clock output
39	VDD	PWR	Power supply, nominal 3.3V
40	OE_INV	IN	This latched input selects the polarity of the OE pins.
40	OE_IIV	IIN	0 = OE pins active high, 1 = OE pins active low (OE#)
41	DIF_7#	OUT	0.7V differential Complementary clock output
42	DIF_7	OUT	0.7V differential true clock output
43	OE4#	IN	Active low input for enabling DIF pair 4
	OL+#	111	1 =disable outputs, 0 = enable outputs
44	OE7#	IN	Active low input for enabling DIF pair 7.
	102,"		1 =disable outputs, 0 = enable outputs
45	LOCK	OUT	3.3V output indicating PLL Lock Status. This pin goes high when lock is achieved.
			This pin establishes the reference for the differential current-mode
46 IREF		IN	output pairs. It requires a fixed precision resistor to ground. 475ohm is
10	INEF	l IIN	the standard value for 100ohm differential impedance. Other
			impedances require different values. See data sheet.
47	GNDA	PWR	Ground pin for the PLL core.
48	VDDA	PWR	3.3V power for the PLL core.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the ICS9DB803D. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Symbol	Parameter	Min	Max	Units
VDDA/R	3.3V Core Supply Voltage		4.6	V
VDD	3.3V Logic Supply Voltage		4.6	V
V_{IL}	Input Low Voltage	GND-0.5		V
V_{IH}	Input High Voltage		V _{DD} +0.5V	V
Ts	Storage Temperature	-65	150	°C
Tambient	Commerical Operating Range	0	70	°C
Tambient	Industrial Operating Range	-40	85	°C
Tcase	Case Temperature		115	°C
	Input ESD protection			
ESD prot	human body model	2000		V

Electrical Characteristics-Clock Input Parameters

 T_A = Tambient for the desired operating range, Supply Voltage V_{DD} = 3.3 V +/-5%

TA = Tambient for the desired operating range, Supply Voltage V _{DD} = 5.5 V +/-5%									
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES		
Input High Voltage - DIF_IN	V _{IHDIF}	Differential inputs (single-ended measurement)	600	800	1150	mV	1		
Input Low Voltage - DIF_IN	V _{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1		
Input Common Mode Voltage - DIF_IN	V_{COM}	Common Mode Input Voltage	300		1000	mV	1		
Input Amplitude - DIF_IN	V _{SWING}	Peak to Peak value (single-ended measurement)	300		1450	mV	1		
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2		
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}$, $V_{IN} = GND$	-5		5	uA	1		
Input Duty Cycle	d _{tin}	Measurement from differential wavefrom	45		55	%	1		
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		125	ps	1		

¹ Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through Vswing min centered around differential zero

Electrical Characteristics-Input/Supply/Common Output Parameters

 T_A = Tambient for the desired operating range, Supply Voltage V_{DD} = 3.3 V +/-5%

TA = Tamble III Tol the des	neu operani	ig range, Supply voltage $v_{DD} = 3.3 \text{ v} + 7.5\%$	0				
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V _{IHSE}	_	2		$V_{DD} + 0.3$	V	1
Input Low Voltage	V _{ILSE}	Single Ended Inputs, 3.3 V +/-5%	GND - 0.3		0.8	V	1
Input High Current	I _{IHSE}	$V_{IN} = V_{DD}$	-5		5	uA	1
input riigir Curient	_	$V_{IN} = 0 \text{ V}$; Inputs with no pull-up resistors	-5		3	uA	1
Input Low Current	I _{IL1}						
	I _{IL2}	V _{IN} = 0 V; Inputs with pull-up resistors	-200			uA	1
ODDOOC Complet Comment	I _{DD3.3OPC}	Full Active, C _L = Full load; Commerical Temp Range		175	200	mA	1
9DB803 Supply Current	I _{DD3.3OPI}	Full Active, C _L = Full load; Industrial Temp Range		190	225	mA	1
		all diff pairs driven, C-Temp		50	60	mA	1
9DB803 Powerdown	I _{DD3.3PDC}	all differential pairs tri-stated, C-Temp		4	6	mA	1
Current	,	all diff pairs driven, I-temp		55	65	mA	1
	I _{DD3.3PDI}	all differential pairs tri-stated, I-temp		6	8	mA	1
	I _{DD3.3OPC}	Full Active, C _L = Full load; Commerical Temp Range		105	125	mA	1
9DB403 Supply Current	I _{DD3.3OPI}	Full Active, C _L = Full load; Industrial		115	150	mA	1
		Temp Range all diff pairs driven, C-Temp		25	30	mΛ	1
9DB403 Powerdown	I _{DD3.3PDC}	all differential pairs tri-stated, C-Temp		25	30	mA mA	1
Current		all diff pairs driven, I-Temp		30	35	mA	1
Odifont	I _{DD3.3PDI}	all differential pairs tri-stated, I-Temp		3	4	mA	1
	F	PCIe Mode (Bypass#/PLL= 1)	50		100	MHz	1
Input Frequency	F _{iPLL}						
D: 1 1 .	F _{iBYPASS}	Bypass Mode ((Bypass#/PLL= 0)	33		400	MHz	1
Pin Inductance	L _{pin}				7	nH –	1
	C _{IN}	Logic Inputs, except SRC_IN	1.5		5	pF	1
Capacitance	C _{INSRC_IN}	SRC_IN differential clock inputs	1.5		2.7	pF	1,4
	C _{OUT}	Output pin capacitance			6	pF	1
PLL Bandwidth	BW	-3dB point in High BW Mode	2	2 3 4 MH		MHz	1
1 LL Danamati	5,,	-3dB point in Low BW Mode	0.7	1	1.4	MHz	1
PLL Jitter Peaking	t _{JPEAK}	Peak Pass band Gain		1.5	2	dB	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Input SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	cycles	1,3
Tdrive_SRC_STOP#	t _{DRVSTP}	DIF output enable after SRC_Stop# de-assertion			10	ns	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after			300	us	1,3
Tfall		PD# de-assertion			F	no	1
Tfall	t _F	Fall time of PD# and SRC_STOP#			5	ns	1
Trise	t _R	Rise time of PD# and SRC_STOP#			5	ns	2
SMBus Voltage	V _{MAX}	Maximum input voltage			5.5	V	1
Low-level Output Voltage	V _{OL}	@ I _{PULLUP}			0.4	V	1
Current sinking at V _{OL}	I _{PULLUP}		4			mA	1
SCLK/SDATA	t _{RSMB}	(Max VIL - 0.15) to			1000	ns	1
Clock/Data Rise Time	FINOINID	(Min VIH + 0.15)					<u> </u>
SCLK/SDATA Clock/Data Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1,5

 $^{^1\}mbox{Guaranteed}$ by design and characterization, not 100% tested in production.

²See timing diagrams for timing requirements.

³Time from deassertion until outputs are >200 mV

⁴SRC_IN input

⁵The differential input clock must be running for the SMBus to be active

Electrical Characteristics-DIF 0.7V Current Mode Differential Pair

 T_A =Tambient; V_{DD} = 3.3 V +/-5%; C_L =2pF, R_S =33 Ω , R_P =49.9 Ω , R_{REF} =475 Ω

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo ¹		3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal using oscilloscope	660		850	mV	1,2
Voltage Low	VLow	math function.	-150		150	'''V	1,2
Max Voltage	Vovs	Measurement on single ended			1150	mV	1
Min Voltage	Vuds	signal using absolute value.	-300			111 V	1
Crossing Voltage (abs)	Vcross(abs)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Rise Time	t _r	$V_{OL} = 0.175V, V_{OH} = 0.525V$	175		700	ps	1
Fall Time	t _f	$V_{OH} = 0.525V V_{OL} = 0.175V$	175		700	ps	1
Rise Time Variation	d-t _r				125	ps	1
Fall Time Variation	d-t _f				125	ps	1
Duty Cycle	d _{t3}	Measurement from differential wavefrom	45		55	%	1
Skew, Input to Output	t _{pdBYP}	Bypass Mode, V _T = 50%	2500		4500	ps	1
Skew, input to Output	t _{pdPLL}	PLL Mode V _T = 50%	-250		250	ps	1
Skew, Output to Output	t _{sk3}	V _T = 50%			50	ps	1
Jitter, Cycle to cycle	+.	PLL mode			50	ps	1,3
Jitter, Cycle to cycle	t _{jcyc-cyc}	Additive Jitter in Bypass Mode			50	ps	1,3
		PCIe Gen1 phase jitter (Additive in Bypass Mode)		7	10	ps (pk2pk)	1,4,5
	t _{jphaseBYP}	PCIe Gen 2 Low Band phase jitter (Additive in Bypass Mode)		0	0.1	ps (rms)	1,4,5
Jitter, Phase		PCIe Gen 2 High Band phase jitter (Additive in Bypass Mode)		0.3	0.5	ps (rms)	1,4,5
		PCIe Gen 1 phase jitter		40	86	ps (pk2pk)	1,4,5
	t _{jphasePLL}	PCIe Gen 2 Low Band phase jitter		1.5	3	ps (rms)	1,4,5
		PCIe Gen 2 High Band phase jitter		2.7/ 2.2	3.1	ps (rms)	1,4,5,6

¹Guaranteed by design and characterization, not 100% tested in production.

 $^{^{2}\,}I_{REF} = V_{DD}/(3xR_{R}). \ \ \, \text{For} \; R_{R} = 475\Omega \; (1\%), \; I_{REF} = 2.32 \text{mA}. \; I_{OH} = 6 \; x \; I_{REF} \; \text{and} \; V_{OH} = 0.7V \; @ \; Z_{O} = 50\Omega.$

³ Measured from differential waveform

⁴ See http://www.pcisig.com for complete specs

⁵ Device driven by 932S421C or equivalent.

⁶ First number is High Bandwidth Mode, second number is Low Bandwidth Mode

Clock Periods-Differential Outputs with Spread Spectrum Enabled

	urement	4.01					_	4.00		
WI	ndow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock	1	
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+		
		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Def	finition	Minimum Absolute Period	Minimum Absolute Period	Minimum Absolute Period	Nominal	Maximum	Maximum	Maximum	Unite	Notes
	DIF 100	9.87400	9.99900	9.99900	10.00000	10.00100	10.05130	10.17630	ns	1,2,3
e	DIF 133	7.41425	7.49925	7.49925	7.50000	7.50075	7.53845	7.62345	ns	1,2,4
Name	DIF 166	5.91440	5.99940	5.99940	6.00000	6.00060	6.03076	6.11576	ns	1,2,4
 	DIF 200	4.91450	4.99950	4.99950	5.00000	5.00050	5.02563	5.11063	ns	1,2,4
Signal	DIF 266	3.66463	3.74963	3.74963	3.75000	3.75038	3.76922	3.85422	ns	1,2,4
S	DIF 333	2.91470	2.99970	2.99970	3.00000	3.00030	3.01538	3.10038	ns	1,2,4
	DIF 400	2.41475	2.49975	2.49975	2.50000	2.50025	2.51282	2.59782	ns	1,2,4

Clock Periods-Differential Outputs with Spread Spectrum Disabled

Meas	urement									
Wi	ndow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+		
-		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Def	inition	Minimum	Minimum	Minimum						
		Absolute	Absolute	Absolute	Nominal	Maximum	Maximum	Maximum		
		Period	Period	Period					Units	Notes
	DIF 100	9.87400		9.99900	10.00000	10.00100		10.17630	ns	1,2,3
Je	DIF 133	7.41425		7.49925	7.50000	7.50075		7.62345	ns	1,2,4
lan	DIF 166	5.91440		5.99940	6.00000	6.00060		6.11576	ns	1,2,4
N K	DIF 200	4.91450		4.99950	5.00000	5.00050		5.11063	ns	1,2,4
Signal Name	DIF 266	3.66463		3.74963	3.75000	3.75038		3.85422	ns	1,2,4
Si	DIF 333	2.91470		2.99970	3.00000	3.00030		3.10038	ns	1,2,4
	DIF 400	2.41475		2.49975	2.50000	2.50025		2.59782	ns	1,2,4

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK409/CK410/CK505 accuracy requirements. The 9DB403/803 itself does not contribute to ppm error.

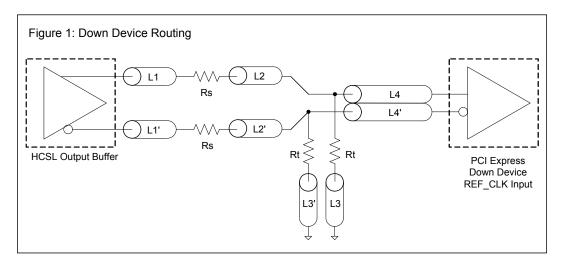
³ Driven by SRC output of main clock, PLL or Bypass mode

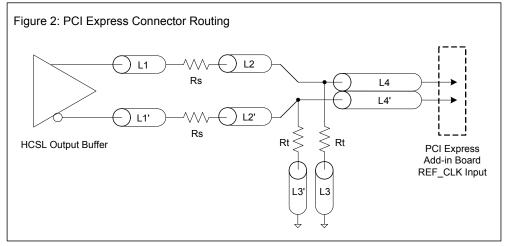
⁴ Driven by CPU output of CK410/CK505 main clock, **Bypass mode only**

SRC Reference Clock								
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure					
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1					
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1					
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1					
Rs	33	ohm	1					
Rt	49.9	ohm	1					

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

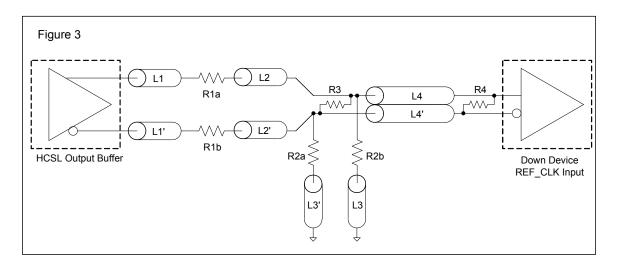
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



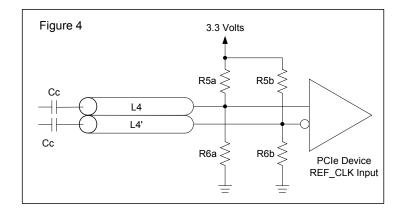


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)										
Vdiff	Vp-p	Vcm	R1	R2	R3	R4	Note				
0.45v	0.22v	1.08	33	150	100	100					
0.58	0.28	0.6	33	78.7	137	100					
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible				
0.60	0.3	1.2	33	174	140	100	Standard LVDS				

R1a = R1b = R1 R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)							
Component	Value	Note					
R5a, R5b	8.2K 5%						
R6a, R6b	1K 5%						
Cc	0.1 μF						
Vcm	0.350 volts						



General SMBus Serial Interface Information

How to Write

- · Controller (host) sends a start bit
- · Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- · IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

Index Block Write Operation								
Controll	er (Host)		IDT (Slave/Receiver)					
Т	starT bit							
Slave A	Address							
WR	WRite							
			ACK					
Beginning	Byte = N							
			ACK					
Data Byte	Count = X							
			ACK					
Beginnin	g Byte N							
			ACK					
0		×						
0		X Byte	0					
0		Ö	0					
			0					
Byte N	Byte N + X - 1							
			ACK					
Р	stoP bit							

Read Address	Write Address
DD _(H)	DC _(H)

How to Read

- · Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- · Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- · Controller (host) will need to acknowledge each byte
- · Controller (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

	Index Block Read Operation						
Cor	ntroller (Host)		IDT (Slave/Receiver)				
T starT bit							
SI	ave Address						
WR	WRite						
			ACK				
Begi	nning Byte = N						
			ACK				
RT	Repeat starT						
SI	ave Address						
RD	ReaD						
			ACK				
			Data Byte Count=X				
	ACK						
			Beginning Byte N				
	ACK						
		<u>e</u>	0				
	0	X Byte	0				
	0	×	0				
	0						
			Byte N + X - 1				
N	Not acknowledge						
Р	P stoP bit						

SMBus Table: Frequency Select Register, READ/WRITE ADDRESS (DC/DD)

Byt	Byte 0 Pin # Name		Control Function		0	1	PWD
Bit 7	7 - PD_Mode		PD# drive mode	RW	driven	Hi-Z	0
Bit 6	6 - STOP_Mode		DIF_Stop# drive mode	RW	driven	Hi-Z	0
Bit 5	- Reserved		Reserved	RW	RW Reserved		Χ
Bit 4	-	Reserved	Reserved	RW	Reserved		Χ
Bit 3	-	Reserved	Reserved	RW	Reserved		Χ
Bit 2	-	PLL_BW#	Select PLL BW	RW	High BW	Low BW	1
Bit 1	Ī	BYPASS#	BYPASS#/PLL	RW	fan-out	ZDB	1
Bit 0	- SRC_DIV#		SRC Divide by 2 Select	RW	x/2	1x	1

SMBus Table: Output Control Register

Byte 1	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7		DIF_7	Output Enable	RW	Disable	Enable	1
Bit 6		DIF_6	Output Enable	RW	Disable	Enable	1
Bit 5		DIF_5	Output Enable	RW	Disable	Enable	1
Bit 4		DIF_4	Output Enable	RW	Disable	Enable	1
Bit 3		DIF_3	Output Enable	RW	Disable	Enable	1
Bit 2		DIF_2	Output Enable	RW	Disable	Enable	1
Bit 1		DIF_1	Output Enable	RW	Disable	Enable	1
Bit 0		DIF_0	Output Enable	RW	Disable	Enable	1

SMBus Table: OE Pin Control Register Control Register

By	Byte 2 Pin # Name		Name	Control Function		0	1	PWD
Bit 7			DIF_7	DIF_7 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 6			DIF_6	DIF_6 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 5			DIF_5	DIF_5 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 4			DIF_4	DIF_4 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 3			DIF_3	DIF_3 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 2			DIF_2	DIF_2 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 1			DIF_1	DIF_1 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 0			DIF_0	DIF_0 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0

SMBus Table: Reserved Register

Byte 3 Pin #		Name	Control Function	Type	0	1	PWD	
Bit 7			Reserved	RW	Reserved		X	
Bit 6				Reserved	RW	Reserved		X
Bit 5				Reserved	RW	Reserved		X
Bit 4				Reserved	RW	Reserved		X
Bit 3				Reserved	RW	Reserved		X
Bit 2				Reserved	RW	Rese	erved	X
Bit 1				Reserved	RW	Reserved		X
Bit 0				Reserved	RW	Rese	erved	X

14

SMBus Table: Vendor & Revision ID Register

Byte 4 Pin #		Name	Control Function	Туре	0	1	PWD	
Bit 7	•		RID3		R	ı	-	Χ
Bit 6	•		RID2	REVISION ID	R	-	-	Χ
Bit 5	-		RID1	NEVISION ID	R	-	-	Х
Bit 4	•		RID0		R	-	-	Χ
Bit 3	1		VID3		R	1	-	0
Bit 2	•		VID2	VENDOR ID	R	-	-	0
Bit 1	1		VID1	VENDOR ID	R	1	-	0
Bit 0	•		VID0		R	-	-	1

SMBus Table: DEVICE ID

Byte 5 Pin #		Name	Control Function	Туре	0	1	PWD
Bit 7	-	Device ID 7 (MSB)		RW			0
Bit 6	-		Device ID 6	RW	RW		Х
Bit 5	-	Device ID 5		RW	Device ID	Х	
Bit 4	-		Device ID 4	RW		03 and 43	0
Bit 3	-		Device ID 3	RW		03 and 43 9DB403	0
Bit 2	-		Device ID 2	RW	nex ioi	900403	0
Bit 1	-		Device ID 1				1
Bit 0	-		Device ID 0	RW	7		1

SMBus Table: Byte Count Register

Ву	te 6	Pin #	Name	Control Function	Туре	0	1	PWD
Bit 7	-		BC7		RW	-	-	0
Bit 6	-		BC6	Writing to this register configures how	RW	•	-	0
Bit 5			BC5		RW	•	-	0
Bit 4			BC4		RW	•	-	0
Bit 3			BC3	many bytes will be read back.	RW	•	-	0
Bit 2	-		BC2		RW	-	-	1
Bit 1	- B		BC1]	RW	-	-	1
Bit 0	-		BC0		RW	-	-	1

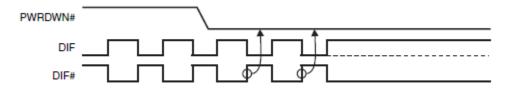
Note: Polarities in timing diagrams are shown OE INV = 0. They are similar to OE INV = 1.

PD#, Power Down

The PD# pin cleanly shuts off all clocks and places the device into a power saving mode. PD# must be asserted before shutting off the input clock or power to insure an orderly shutdown. PD is asynchronous active-low input for both powering down the device and powering up the device. When PD# is asserted, all clocks will be driven high, or tri-stated (depending on the PD# drive mode and Output control bits) before the PLL is shut down.

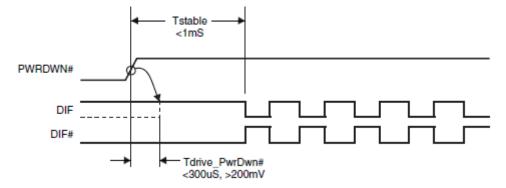
PD# Assertion

When PD# is sampled low by two consecutive rising edges of DIF#, all DIF outputs must be held High, or tri-stated (depending on the PD# drive mode and Output control bits) on the next High-Low transition of the DIF# outputs. When the PD# drive mode bit is set to '0', all clock outputs will be held with DIF driven High with 2 x IREF and DIF# tri-stated. If the PD# drive mode bit is set to '1', both DIF and DIF# are tri-stated.



PD# De-assertion

Power-up latency is less than 1 ms. This is the time from de-assertion of the PD# pin, or VDD reaching 3.3V, or the time from valid SRC_IN clocks until the time that stable clocks are output from the device (PLL Locked). If the PD# drive mode bit is set to '1', all the DIF outputs must driven to a voltage of >200 mV within 300 us of PD# de-assertion.



SRC STOP#

The SRC_STOP# signal is an active-low asynchronous input that cleanly stops and starts the DIF outputs. A valid clock must be present on SRC_IN for this input to work properly. The SRC_STOP# signal is de-bounced and must remain stable for two consecutive rising edges of DIF# to be recognized as a valid assertion or de-assertion.

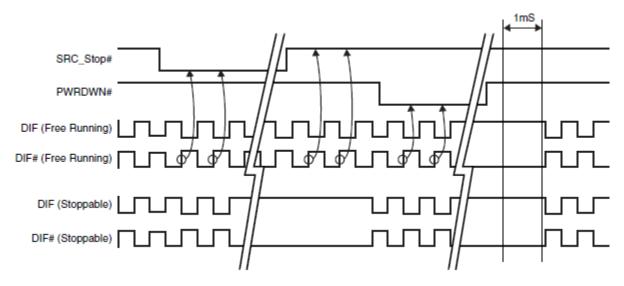
SRC STOP# - Assertion

Asserting SRC_STOP# causes all DIF outputs to stop after their next transition (if the control register settings allow the output to stop). When the SRC_STOP# drive bit is '0', the final state of all stopped DIF outputs is DIF = High and DIF# = Low. There is no change in output drive current. DIF is driven with 6xIREF. DIF# is not driven, but pulled low by the termination. When the SRC_STOP# drive bit is '1', the final state of all DIF output pins is Low. Both DIF and DIF# are not driven.

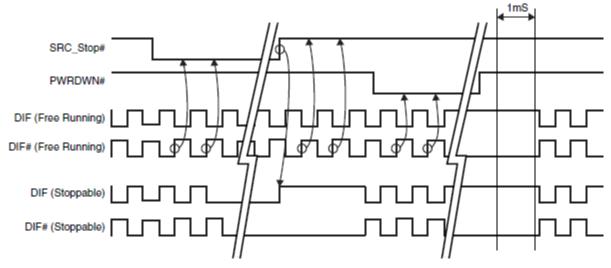
SRC_STOP# - De-assertion (transition from '0' to '1')

All stopped differential outputs resume normal operation in a glitch-free manner. The de-assertion latency to active outputs is 2-6 DIF clock periods, with all DIF outputs resuming simultaneously. If the SRC_STOP# drive control bit is '1' (tri-state), all stopped DIF outputs must be driven High (>200 mV) within 10 ns of de-assertion.

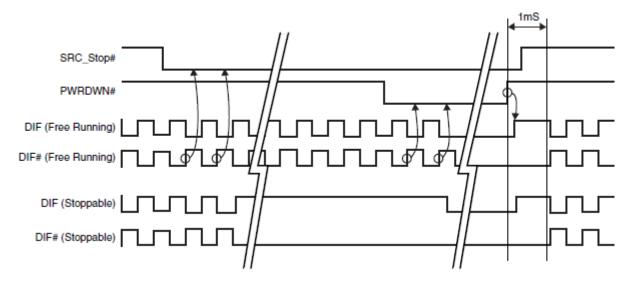
SRC_STOP_1 (SRC_Stop = Driven, PD = Driven)



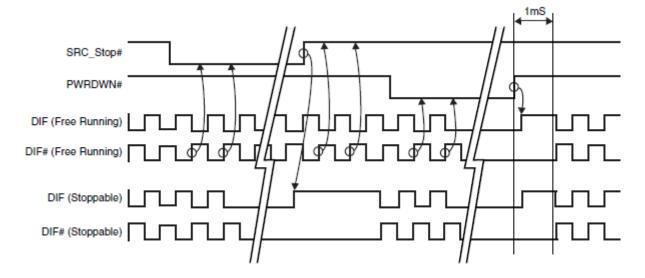
SRC STOP 2 (SRC Stop =Tristate, PD = Driven)



SRC_STOP_3 (SRC_Stop = Driven, PD = Tristate)

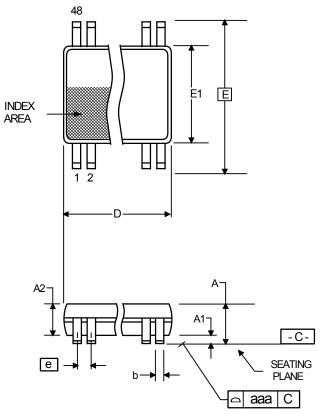


SRC_STOP_4 (SRC_Stop = Tristate, PD = Tristate)



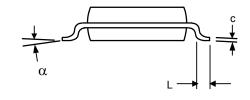
Package Outline and Package Dimensions (48-pin TSSOP)

Package dimensions are kept current with JEDEC Publication No. 95



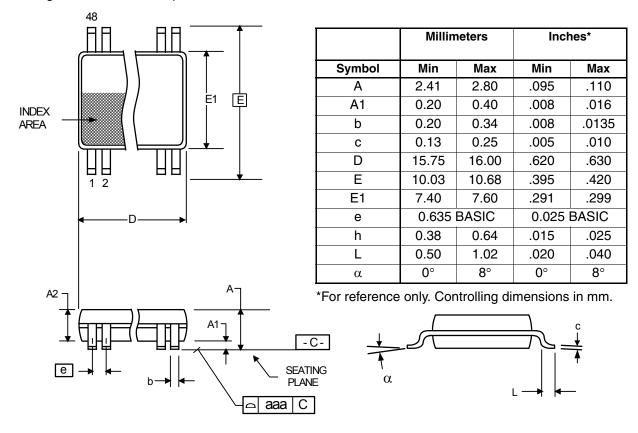
	Millimeters		Inch	nes*
Symbol	Min	Max	Min	Max
Α		1.20		0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
b	0.17	0.27	0.007	0.011
С	0.09	0.20	0.0035	0.008
D	12.40	12.60	0.488	0.496
Е	8.10 E	BASIC	0.319 BASIC	
E1	6.00	6.20	0.236	0.244
е	0.50	Basic	0.020	Basic
L	0.45	0.75	0.018	0.030
α	0°	8°	0°	8°
aaa		0.10		0.004

^{*}For reference only. Controlling dimensions in mm.



Package Outline and Package Dimensions (48-pin SSOP)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
9DB803DGLF	9DB803DGLF	Tubes	48-pin TSSOP	0 to +70° C
9DB803DGLFT	9DB803DGLF	Tape and Reel	48-pin TSSOP	0 to +70° C
9DB803DGILF	9DB803DGILF	Tubes	48-pin TSSOP	-40 to +85° C
9DB803DGILFT	9DB803DGILF	Tape and Reel	48-pin TSSOP	-40 to +85° C
9DB803DFLF	9DB803DFLF	Tubes	48-pin SSOP	0 to +70° C
9DB803DFLFT	9DB803DFLF	Tape and Reel	48-pin SSOP	0 to +70° C
9DB803DFILF	9DB803DFILF	Tubes	48-pin SSOP	-40 to +85° C
9DB803DFILFT	9DB803DFILF	Tape and Reel	48-pin SSOP	-40 to +85° C

[&]quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

While the information presented herein has been checked for both accuracy and reliability, Integrated Device Technology (IDT) assumes no responsibility for either its use or for the infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial applications. Any other applications such as those requiring extended temperature range, high reliability, or other extraordinary environmental requirements are not recommended without additional processing by IDT. IDT reserves the right to change any circuitry or specifications without notice. IDT does not authorize or warrant any IDT product for use in life support devices or critical medical instruments.

[&]quot;D" is the device revision designator (will not correlate with the datasheet revision).

Revision History

Rev.	Issue Date	Issuer	Description	Page #
Α	8/15/2006		Updated electrical characteristics for final data sheet	-
В			Added Input Clock Specs	
С	2/29/2008		Updated Input Clock Specs	
D	3/18/2008		Fixed typo in Input Clock Parameters	
Е	3/28/2008		Updated Electrical Char tables	
F	4/10/2008		Updated Input Clock Specs	
G	1/13/2009		Corrected part ordering information	
			1. Clarified that Vih and Vil values were for Single ended inputs	
			2. Added Differential Clock input parameters.	
			3. Updated Electrical Characteristics to add propagation delay and	
			phase noise information.	
			4. Added SMBus electrical characteristics	
			5. Added foot note about DIF input running in order for the SMBus	
			interface to work	
			6. Added foot note to Byte 1 about functionality of OE bits and OE	
			pins.	
Н	10/7/2009		7. Updated/Reformatted General Description	Various
J	1/27/2011		Updated Termination Figure 4	12
			1. Update pin 2 pin-name and pin description from VDD to VDDR. This	
			highlights that optimal peformance is obtained by treating VDDR as in	
К	5/9/2011		analog pin. This is a document update only, there is no silicon change.	Various
L	8/27/2012		Updated Vswing conditions to include "single-ended measurement"	7
			Updated Byte 2, bits 0~7 per char review. Outputs can be programmed	
М	9/18/2012		with Byte 2 to be Stoppable or Free-Run with DIF_Stop pin, not the OE	14
	0, 10, 20 12		pins.	
			Typo discovered on front page "Output Features" section. Was: "50 –	
N	7/10/2013	R. Wei	110MHz operation in PLL mode"; changed to: "50 – 100MHz operation	1
			in PLL mode"	

SYNTHESIZERS

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers skilled in the art designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only for development of an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising out of your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use o any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.0 Mar 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:

www.renesas.com/contact/